CLAIMS

1. An electrode level difference absorbing print paste, including ceramic powder, a binder resin, a plasticizer and a solvent, wherein

said binder resin contains a polyvinyl butyral resin or a polyacetal resin, a polymerization degree of the resin is 1400 or more, a butyralation degree of the resin is 64 to 74 mol%, and an acetalization degree of the resin is 66 to 74 mol%.

2. The electrode level difference absorbing print paste as set forth in claim 1, wherein said binder resin is contained by 3 parts by weight or more and 9 parts by weight or less with respect to 100 parts by weight of said ceramic powder.

3. The electrode level difference absorbing print paste as set forth in claim 1, wherein said solvent contains at least one of terpineol, dihydroterpineol, terpinyl acetate, dihydroterpinyl acetate and 4-(1'-acetoxy-1'-)cyclohexanol acetate.

4. The electrode level difference absorbing print paste as set forth in any one of claims 1 to 3,

wherein said solvent is contained by 20 to 80 parts by weight with respect to 100 parts by weight of the paste.

5. The electrode level difference absorbing print paste as set forth in any one of claims 1 to 4, wherein viscosity of said electrode level difference absorbing print paste when giving rotation of obtaining a shear rate of 8[1/s] is 4 to 30 Pa·s.

6. The electrode level difference absorbing print paste as set forth in any one of claims 1 to 5, wherein ceramic powder is contained at a rate of 30 to 55 wt% with respect to the entire paste.

7. The electrode level difference absorbing print paste as set forth in any one of claims 1 to 6, containing at least one of phthalate ester [dibutyl phthalate (DBP), diotycl phthalate (DOP), benzylbutyl phthalate (BBP), butyl butylene glycol (BPBG)], adipic acid ester [diotycle adipic acid (DOA)], sebacic acid ester and sebacic dibutyl as said plasticizer.

8. The electrode level difference absorbing print paste as set forth in any one of claims 1 to 7, wherein said plasticizer is contained by 20 to 200 parts

by weight with respect to 100 parts by weight of a binder resin.

9. The electrode level difference absorbing print paste as set forth in any one of claims 1 to 7, containing at least one of a hygroscopic polymer, cation based surfactant (amine based surfactant) and amphoteric surfactant as an antistatic agent.

10. A production method of an electronic device, comprising the steps of:

forming a stacked body by stacking green sheets and electrode layers having a predetermined pattern; and

firing said stacked body;

wherein

before forming said stacked body, a blank pattern layer having a substantially the same thickness as that of said electrode layer is formed a space portion of said electrode layer having a predetermined pattern is formed; and

the electrode level difference absorbing print paste as set forth in any one of claims 1 to 8 is used as an electrode level difference absorbing print paste for forming said blank pattern layer.

11. The production method of an electronic device as set forth in claim 10, wherein ceramic powder included in said electrode level difference absorbing print paste is the same as ceramic powder included in slurry for forming said green sheet.

12. The production method of an electronic device as set forth in claim 10 or 11, wherein a polymerization degree of a binder resin included in said electrode level difference absorbing print paste is 1400 or more.

13. The production method of an electronic device as set forth in any one of claims 10 to 12, wherein a binder resin included in said electrode level difference absorbing print paste is the same as a binder resin included in slurry for forming said green sheet.

14. The production method of an electronic device as set forth in any one of claims 10 to 13, wherein said binder resin is polyvinyl butyral and/or polyvinyl acetal.

15. The production method of an electronic device as set forth in claim 14, wherein when said binder resin is polyvinyl butyral, a butyralation degree of said polyvinyl butyral is in a range of 64 to 74 mol%.

16. The production method of an electronic device as set forth in claim 15, wherein when said binder resin is polyvinyl acetal, an acetalization degree of said polyvinyl acetal is in a range of 66 to 74 mol%.

17. The production method of an electronic device as set forth in any one of claims 10 to 16, wherein said electrode level difference absorbing print paste contains ceramic powder at a rate of 30 to 50 wt% with respect to the entire paste.

18. The production method of an electronic device as set forth in any one of claims 10 to 17, wherein viscosity of said electrode level difference absorbing print paste when giving rotation of obtaining a shear rate of 8[1/s] is 4 to 30 Pa·s.

19. The production method of an electronic device as set forth in any one of claims 10 to 18, wherein said binder resin included in slurry for forming said green sheet includes polyvinyl butyral resin, a polymerization degree of the polyvinyl butyral resin is 1000 or more and 3300 or less, a butyralation degree of the resin is more than 64% and less than 78%, and a residual acetyl group

amount is less than 6%.

20. A production method of an electronic device, comprising the steps of:

forming a stacked body by stacking green sheets and electrode layers having a predetermined pattern; and

firing said stacked body;

wherein before forming said stacked body, a blank pattern layer having a substantially the same thickness as that of said electrode layer is formed on a space portion of said electrode layer having a predetermined pattern;

the electrode level difference absorbing print paste for forming said blank pattern layer includes at least ceramic powder and a binder resin; and

a polymerization degree of the binder resin included in said electrode level difference absorbing print paste is equal to or higher than that of a binder resin included in slurry for forming said green sheet.